

**IN THE UNITED STATES PATENT AND TRADEMARK OFFICE**

**Applicants:** Takashi Nakano et al.      **Examiner:** unassigned  
**Serial No.:** unassigned      **Art Unit:** unassigned  
**Filed:** herewith      **Docket:** 18497  
**For:** SEMICONDUCTOR DEVICE, SEMICONDUCTOR Dated: December 10, 2004  
CIRCUIT AND METHOD OF FABRICATING  
SEMICONDUCTOR DEVICE

Commissioner for Patents  
P. O. Box 1450  
Alexandria, VA 22313-1450

**INFORMATION DISCLOSURE STATEMENT**

Sir:

In accordance with 37 C.F.R. §§1.97 and 1.98, it is requested that the following references, which are also listed on the attached Form PTO-1449, be made of record in the above-identified case.

1. U.S. Patent Application Publication 2002/0024407A1 dated February 28, 2002 to Arai et al.
2. Japanese Laid Open Application 2001-338836 dated December 7, 2001 together with English language abstract.

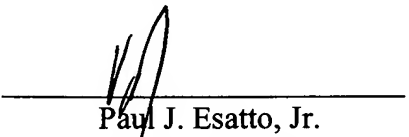
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**CERTIFICATE OF MAILING BY EXPRESS MAIL**

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I hereby certify that this correspondence is being deposited with the United States Postal Service Express Mail Post Office to Addressee service under 37 C.F.R. §1.10 on the date indicated above and is addressed to the Commissioner For Patents, P.O. Box 1450, Alexandria, VA 22313-1450.

Dated: December 10, 2004

  
Paul J. Esatto, Jr.

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3. Japanese Laid Open Application 2001-267751 dated September 28, 2001 together with English language abstract.
4. Japanese Laid Open Application 11-177276 dated July 2, 1999 together with English language abstract.
5. European Patent Publication EP 0 788 118 A1 dated August 6, 1997.
6. U.S. Patent Application Publication 2002/0011606A1 dated January 31, 2002 to Otake et al.
7. Japanese Laid Open Application 6-216309 dated August 5, 1994 together with English language abstract.
8. Japanese Laid Open Application 2001-274314 dated October 5, 2001 together with English language abstract.
9. Japanese Laid Open Application 8-330738 dated December 13, 1996 together with English language abstract.
10. Japanese Laid Open Application 10-270643 dated October 9, 1998 together with English language abstract.
11. Japanese Laid Open Application 2001-168223 dated June 22, 2001 together with English language abstract.
12. Japanese Laid Open Application 6-216309 dated August 5, 1994 together with English language abstract.
13. Japanese Laid Open Application 2002-164760 dated June 7, 2002 together with English language abstract.
14. Japanese Laid Open Application 56-62354 dated May 28, 1981 together with English language abstract.


References 1-9 were cited in a Search Report dated September 9, 2003 received from the Japanese Patent Office, a copy of which is enclosed. The relevance of references 1-9 has been described in the Search Report. References 10-13 are cited in the specification.

Applicant is submitting copies of the above-cited references.

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Inasmuch as this Information Disclosure Statement is being submitted in  
accordance with the schedule set out in 37 C.F.R. § 1.97(b), no statement or fee is required.

Respectfully submitted,



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Form PTO-1449 U.S. DEPARTMENT OF COMMERCE  
(REV. 7-80) PATENT AND TRADEMARK OFFICE

# INFORMATION DISCLOSURE CITATION

*(Use several sheets if necessary)*

Atty. Docket No. (Optional)

18497

Application Number

unassigned

10/518157

Applicant(s)

Takashi Nakano et al.

Filing Date

even date herewith

Group Art Unit

unassigned

## U.S. PATENT DOCUMENTS

EXAMINER INITIAL*	DOCUMENT NUMBER	DATE	NAME	CLASS	SUBCLASS	FILING DATE (if appropriate)
	2002/0024407A1	2/28/02	Arai et al.			
	2002/0011606A1	1/31/02	Otake tal.			

## FOREIGN PATENT DOCUMENTS

	REF	DOCUMENT NUMBER	DATE	COUNTRY	CLASS	SUBCLASS	TRANSLATION	
							YES	NO
		2001-338836	12/7/01	Japan				
		2001-267751	9/28/01	Japan				
		11-177276	7/2/99	Japan				
		EP0788118A1	8/6/97	EPO				
		06-216309	8/5/94	Japan				
		2001-274314	10/5/01	Japan				
		8-330738	12/13/96	Japan				
		10-270643	10/9/98	Japan				
		2001-168223	6/22/01	Japan				
		6-216309	8/5/94	Japan				
		2002-164760	6/7/02	Japan				
		56-062354	5/28/81	Japan				

## OTHER DOCUMENTS *(Including Author, Title, Date, Pertinent Pages, Etc.)*


EXAMINER

DATE CONSIDERED

\* EXAMINER: Initial if reference considered, whether or not citation is in conformance with MPEP 609; draw line through citation if not in conformance and not considered. Include copy of this form with next communication to applicant.